

Call for Papers

Special Issue on *Selected Papers from the IEEE International Conference on Flexible, Printable, Sensors and Systems (FLEPS 2023)*

The scope of this Special Issue (SI) includes publication of a selected number of high-quality reviewed FLEPS 2023 presented papers on a broad range of flexible, printable electronics systems. The authors of the selected papers, as notified by the conference technical program committee, are invited to submit an extended version of FLEPS 2023 presented papers for consideration of publication in the proposed J-FLEX SI. All such submissions will comply with J-FLEX author-guidelines and be subjected to the standard IEEE and J-FLEX publication policy.

Topics

- All areas of Flexible/Printable Electronics
- Stretchable/Shrinkable Sensors and Electronics
- Electronic textile/ paper
- Flexible/Printable Electronics in context with Circular Economy
- Organic/Inorganic/Hybrid Flexible Sensors and Electronics
- Printable batteries, energy harvesters
- Sensors for health monitoring
- Printable displays, lighting sources
- Packaging
- Smart tags, RFID tags, etc.
- Modeling of printable sensors
- Manufacturing Techniques (including Printing)
- Emerging Materials for Flexible and Printable System

Important dates

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|---------------------------|---|
| Nov 2023: | Call for Papers (to appear in IEEE Journal on Flexible Electronics) |
| February 15, 2024: | Deadline for Paper Submission |
| March 31, 2024: | Completion of First Review |
| April 2024: | Completion of Final Review |
| June 2024: | Publication |

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Submission and Peer Review of Papers

All papers shall undergo the standard IEEE J-FLEX peer-review process. Manuscripts must be submitted online, via the *IEEE Manuscript Central*TM, see <https://mc.manuscriptcentral.com/jflex>. When submitting, please indicate in the “Manuscript Type” roll down menu, and also by e-mail to Mansi Kukreti, m.kukreti@ieee.org, that the paper is intended for the **FLEPS 2023** Special Issue. Authors are particularly encouraged to **suggest names of potential reviewers** for their manuscripts in the space provided for these recommendations in *Manuscript Central*. For manuscript preparation and submission, please follow the guidelines in the *Information for Authors* at the IEEE J-FLEX web page, <https://ieee-jflex.org/guidelines-for-authors/>. Please also refer to guidelines for conference based special issues, [here](#).